

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1135acsw#trpbf

(Engineering Calculation)

SOIC WIDE

(printed on: 2020-07-11 18:17:51)

TOTAL MASS (g) : 0.544966

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.006856 | 1000000 | 12580.609375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.153163 | 975000 | 281050.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003770 | 24000 | 6917.86669922 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000047 | 300 | 86.2439651489 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000110 | 700 | 201.847579956 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.157090 | 1000000 | 288256.6875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005974 | 1000000 | 10961.5664062 | | |
| | | External Plating Total: | | | | 0.005974 | 1000000 | 10961.5664062 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001257 | 1000000 | 2306.56738281 | | |
| Internal Plating Total: | | | | 0.001257 | 1000000 | 2306.56738281 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001682 | 750000 | 3086.43286133 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000561 | 250000 | 1029.42260742 | | |
| Die Attach Total: | | | | 0.002243 | 1000000 | 4115.85595703 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.038213 | 103000 | 70120.015625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.332045 | 895000 | 609295.25 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000742 | 2000 | 1361.55371094 | | |
| | | Encapsulation Total: | | | | 0.371000 | 1000000 | 680776.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000546 | 1000000 | 1001.89794922 | | |
| | | | | | TOTAL MASS (g) : | 0.544966 | | |